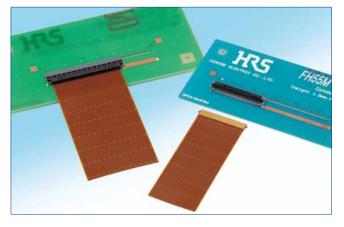
0.4/0.5mm Pitch, 1.5mm Height Lower Contact, Front Flip for High-Speed Transmission

FH55/FH55M Series



Features

- **1.** High-Speed Transmission(10⁺ Gbps) FPC Connectors
- Capable of transmitting high-speed differential signals by arranging signal contacts (S) and ground contacts (G) in the sequence of GSSG. (10⁺ Gbps) (The GSSG layout utilizes differential signals, but the contacts can also be designated for other uses other than differential signals.)

2. Impedance Matched-Contact Design

The signal contacts were designed with impedance control in mind and to realize superior high-speed transmission feature.(Fig.2)

3. Fully Enclosed Molded Structure (Over molding Structure) Board space under the connector can be utilized in patterning since the bottom of the connector is covered with resin and enhances PCB flexibility.

4. Flip-Lock System Provides Reliability and FPC Security

The Flip-lock (one-touch rotational lock) ZIF structure allows for a reliable and simple to secure FPC connection operation. Utilizing a clear clicking feeling at the time of locking prevents an incomplete lock.

5. Easy FPC insertion

The FPC guiding system utilizes guide tabs that enable a temporary hold while FPC is inserted and accurately determines mating location all while ensuring a consistent connection.

6. Compatible with 0.3mm Thick FPC

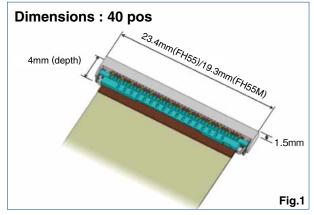
This connector utilizes 0.3mm thick FPC, which is the standard thickness of a 0.5mm pitch connector (Appropriate stiffness with reinforcing board prevents FPC deformation, preventing troubles at times of insertion and mating).

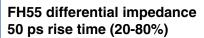
7. Automatic Mounting Option Available

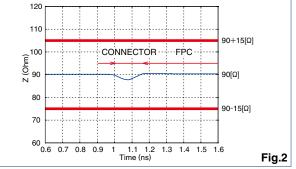
Emboss packaging makes automatic mounting possible (5,000 pcs/reel).

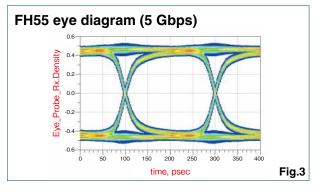
8. Halogen-free

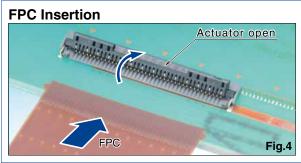
Chlorine and bromine are not used in amounts that exceed the standard values in these connectors. * Defined according to IEC 61249-2-21 Br : 900ppm or below ; CI : 900pm or below ; Br + CI : 1,500ppm or below













2023.07 HS 1

In cases where the application will demand a high level of reliability, such as automotive, please contact a company representative for further information.

Product Specifications

	ratingt	0.5A (0.5mm pitch products)(Note 1) 0.4A (0.4mm pitch products)(Note 1)		Storage temperature range	-10 to +50°C (Note 3)
J	Voltage	AC 50V rms (0.5mm pitch products) AC 40V rms (0.4mm pitch products)	RH 90% or less (no condensation)		RH 90% or less (no condensation)

Suitable FPC/FFC contact specifications

t = 0.3 \pm 0.03 gold-plated

Items	Specifications	Conditions
1.Insulation Resistance	500MΩ min	Measured at DC 100V
2.Withstanding Voltage	No flashover or breakdown	AC 150Vrms applied for 1 minute
3.Contact Resistance	100mΩ max * Including FPC conductor resistance	Measured at 1mA
4.Repeat Performance	100m Ω max No breakage, cracking, or loosening to parts	20 times
5.Vibration Resistance	No electric outage of 1μ or greater Contact resistance : $100m\Omega$ max No breakage, cracking, or loosening to parts	10 cycles in each of three directions at frequency 10-55 Hz, half amplitude 0.75mm
6.Shock Resistance	No electric outage of 1μ or greater Contact resistance : $100m\Omega$ max No breakage, cracking, or loosening to parts	Acceleration of 981m/s ² ; duration 6ms, sine half- wave, 3 cycles in each of the 3 axes each in both directions
7.Humidity Resistance in Steady State	Contact Resistance : $100m\Omega$ max Insulation Resistance : $50M\Omega$ min No breakage, cracking, or loosening to parts	96 hours at temperature 40°C and humidity 90-95%
8.Temperature Cycle	Contact Resistance $: 100m\Omega$ max Insulation Resistance $: 50M\Omega$ min No breakage, cracking, or loosening to parts	Temperature : -55° C $\rightarrow +15^{\circ}$ C to $+35^{\circ}$ C $\rightarrow +85^{\circ}$ C $\rightarrow +15^{\circ}$ to $+35^{\circ}$ C Time : 30 \rightarrow 2 to 3 \rightarrow 30 \rightarrow 2 to 3 minutes 5 cycles with the above conditions
9.Solder Heat Resistance	No marked instability in contacts, or appearance of deformation.	 Reflow : Peak temperature MAX 250°C, 230°C or greater for 60 seconds Soldering iron : 350±10°C for 5 seconds

Note 1 : Use at 70% of the current rating when all pins are energized with current rating.

Note 2 : Temperature rise at the time of electrification is included.

Note 3 : The term "storage" refers to the long-term storage condition of unused products before board mounting. The operating temperature and humidity ranges apply to non-energized state after board mounting.

Materials / Finish

Part	Materials	Color/finish	Remarks
Insulator	LCP	Gray	UL94V-0
Insulator	LOF	Black	01940-0
Contact	Phosphor bronze	Gold-plating	
Metal Parts	Brass	Pure tin reflow plating	

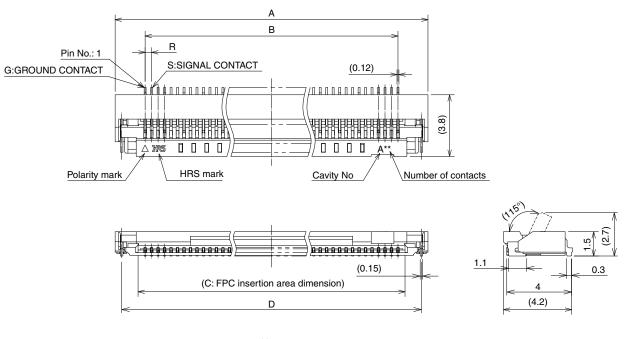
Product Number Structure



Series name : FH	4 Number of contacts : 10 to 61 positions (0.5mm pitch products)
Ø Series No. : 55	10 to 79 positions (0.4mm pitch products)
3 No symbol : 0.5mm pitch products	6 Contact pitch : 0.5mm or 0.4mm
M : 0.4mm pitch products	 Contact Form SH : SMT horizontal mounting type

Connector dimensional drawing





Notes : 1. The dimensions in parentheses () are reference values.

- 2. The lead co-planarity of connector and reinforcing metal part is MAX 0.1mm.
- 3. This product is emboss-packaged. See the package specification diagram for details.
- 4. Dimensions may be changed for sink mark prevention due to improvement, etc.
- 5. Black dots, etc. may occur in mold resin but do not create a quality problem.
- This product is the halogen-free product. (Br content rate: 900 ppm or less; CI content rate: 900ppm or less; Br + CI total content rate: 1,500ppm or less)
- 7. See the table below for available pin arrangements.
- S : SIGNAL CONTACT G : GROUND CONTACT
- * Pins are arranged in the sequence of GSSG to manage high-speed differential signals ; however, all contacts can be used as signals for normal signals other than high-speed signals. Please contact our sales representative for any questions.

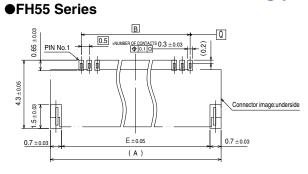
Pin No.	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18	19	20	21	22	23	24	25	26	27	28	29	30	31	32	33	34	35
Pin assignment	G	S	S	G	S	S	G	S	S	G	S	S	G	S	S	G	s	S	G	S	S	G	S	S	G	S	S	G	S	S	G	s	S	G	S
	36	37	38	39	40	41	42	43	44	45	46	47	48	49	50	51	52	53	54	55	56	57	58	59	60	61	62	63	64	65	66	67	68	69	70
	S	G	S	S	G	S	S	G	S	S	G	S	s	G	S	S	G	S	S	G	S	s	G	S	S	G	S	S	G	S	S	G	S	S	G
	71	72	73	74	75	76	77	78	79																										
	S	S	G	S	S	G	S	S	G																										

Unit : mm

								-		
Part No.	HRS No.	No. of contacts	No. of signal contacts	No. of ground contacts	А	В	С	D	R	
FH55-10S-0.5SH	Under planning	10	6	4	8.4	4.5	5.57	7.59		
FH55-22S-0.5SH	580-3707-7 00	22	14	8	14.4	10.5	11.57	13.59		
FH55-31S-0.5SH	580-3704-9 00	31	20	11	18.9	15	16.07	18.09	0.5	
FH55-40S-0.5SH	580-3700-8 00	40	26	14	23.4	19.5	20.57	22.59	0.5	
FH55-49S-0.5SH	Under planning	49	32	17	27.9	24	25.07	27.09		
FH55-61S-0.5SH	Under planning	61	40	21	33.9	30	31.07	33.09		
FH55M-10S-0.4SH	580-3710-0 00	10	6	4	7.3	3.6	4.47	6.49		
FH55M-19S-0.4SH	Under planning	19	12	7	10.9	7.2	8.07	10.09		
FH55M-31S-0.4SH	580-3711-0 00	31	20	11	15.7	12	12.87	14.89		
FH55M-40S-0.4SH	580-3706-4 00	40	26	14	19.3	15.6	16.47	18.49	0.4	
FH55M-49S-0.4SH	Under planning	49	32	17	22.9	19.2	20.07	22.09		
FH55M-61S-0.4SH	Under planning	61	40	21	27.7	24	24.87	26.89		
FH55M-79S-0.4SH	Under planning	79	52	27	34.9	31.2	32.07	34.09		

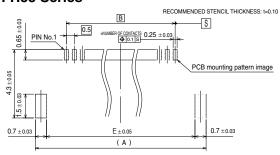
The products above without a HRS No. are currently under planning. Please contact our sales representative for questions concerning the number of contacts.

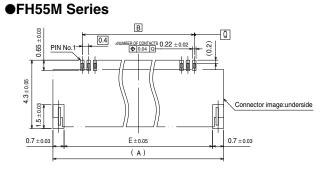
Recommended PCB mounting pattern



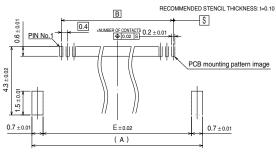
Recommended Stencil pattern

●FH55 Series

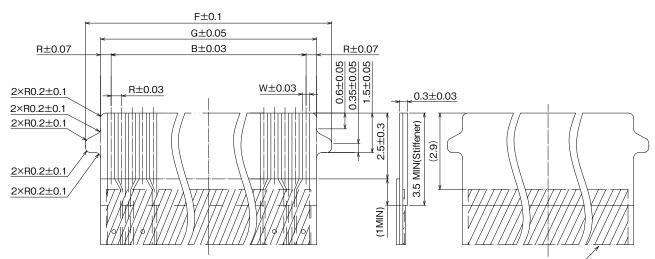




●FH55M Series



Recommended FPC dimensional drawing



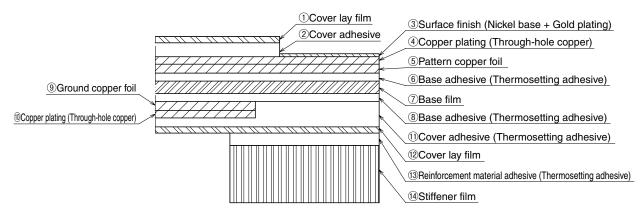
Ground copper foil

Unit : mm

Part No.	HRS No.	No. of contacts	No. of signal contacts	No. of ground contacts	Е	F	G	R	W
FH55-10S-0.5SH	Under planning	10	6	4	7	6.65	5.5		
FH55-22S-0.5SH	580-3707-7 00	22	14	8	13	12.65	11.5		
FH55-31S-0.5SH	580-3704-9 00	31	20	11	17.5	17.15	16	0.5	0.37
FH55-40S-0.5SH	580-3700-8 00	40	26	14	22	21.65	20.5	0.5	0.37
FH55-49S-0.5SH	Under planning	49	32	17	26.5	26.15	25		
FH55-61S-0.5SH	Under planning	61	40	21	32.5	32.15	31		
FH55M-10S-0.4SH	580-3710-0 00	10	6	4	5.9	5.55	4.4		
FH55M-19S-0.4SH	Under planning	19	12	7	9.5	9.15	8		
FH55M-31S-0.4SH	580-3711-0 00	31	20	11	14.3	13.95	12.8		
FH55M-40S-0.4SH	580-3706-4 00	40	26	14	17.9	17.55	16.4	0.4	0.27
FH55M-49S-0.4SH	Under planning	49	32	17	21.5	21.15	20		
FH55M-61S-0.4SH	Under planning	61	40	21	26.3	25.95	24.8		
FH55M-79S-0.4SH	Under planning	79	52	27	33.5	33.15	32		

The products above without a HRS No. are currently under planning. Please contact our sales representative for questions concerning the number of contacts.

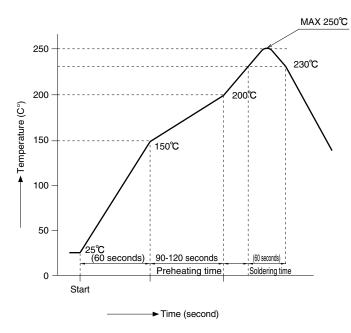
● FH55/FH55M Series FPC Material Constitution (Recommended Specifications)



	Mate	erial Thickness	s (μm)]
Names of Materials	LCP	PI	PI	2
(1) Cover lov film	2-layer CCL 12.5	2-layer CCL 12.5	3-layer CCL 12.5	
1)Cover lay film			-	
②Cover adhesive	28	28	28	-
③Surface treatment (nickel base + gold plating)	(6)	(6)	(6)	
④Copper plating (through-hole copper)	15	15	15	
5 Pattern copper foil	9	18	18	
6 Base adhesive	-	-	16	
⑦Base film < 2	50	25	25	
[®] Base adhesive	-	-	16	
	9	18	18	-
Opper plating (through-hole copper)	15	15	15	
①Cover adhesive	28	28	28	
⁽²⁾ Cover lay film	12.5	12.5	12.5]
⁽³⁾ Reinforcement material adhesive (Thermosetting adhesive)	50	50	30	
19Stiffener film	125	150	125	
Total (Mating Area Thickness: Total of $(3{\sim}(8)$ and $(1{\sim}(4))$	295.5	304.5	291.5]

- Notes 1 : The FPC material constitution is a reference example. Please make the thickness of FPC mating area 0.3±0.03 mm by referring to this material constitution.
- It is a reference example of the base film material. LCP refers to liquid crystal polymer, and PI for polyimide.

Temperature Profile



Applicable Conditions

Reflow System	: Far-infrared, hot-air reflow
Reflow chambe	er atmosphere : Air
Solder	: Paste type Sn/3.0Ag/0.5 Cu
	(M705-221CM5-42-10.5;
	Senju Metal Industry Co., Ltd.)
Test Board	: Board material and size
	Glass epoxy 30 x 60 x 1.0mm
	Land dimensions
	Contact area: 0.3 x 0.65
	Metal part area: 0.7 x 1.5mm
Metal Mask	: Thickness 0.1 mm
	Aperture Dimension
	Contact area 0.25 x 0.65
	Metal part area 0.7 x 1.5mm

The temperature profile shown above is based on the above applicable conditions.

Due to the changing conditions such as solder paste types, manufacturers, board size and other soldering materials, please check to ensure the proper soldering conditions before use.

HS 5

●Package Specifications

Emboss carrier tape dimensional drawing

8±0.1

\$1.5°81

1.75±0.1

J<u></u>±0.

(1.5: Automatic mounting vacuum pickup area)

Ē

L±0.3

(Tape width: 24mm or less)

2±0.1

φ

(4.05) (4.95)

Pulling direction

•

 $\phi \downarrow \phi$

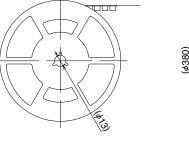
<u>4±0.1</u>

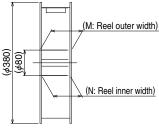
 $\phi + \phi$

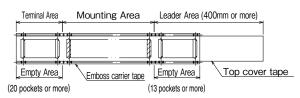
 $\Phi | \Phi$

(Tape width: 32mm or more) 1.75±0.1 2±0.1 ,8<u>±0.1</u> 4±0.1 \$1.5°° ϕ ø (1.9) φ ϕ ÷ -0 (0.3) J±0.1 Ē L±0.3 K±0.1 ÷₩±₽ ϕ ¢ đ 1.7^{+0.15} (1.5: Automatic mounting vacuum pickup area) $1.5^{+0.1}_{0}$ (4.05) (4.95) \geq Pulling direction

Reel state dimensional drawing







Unit : mm

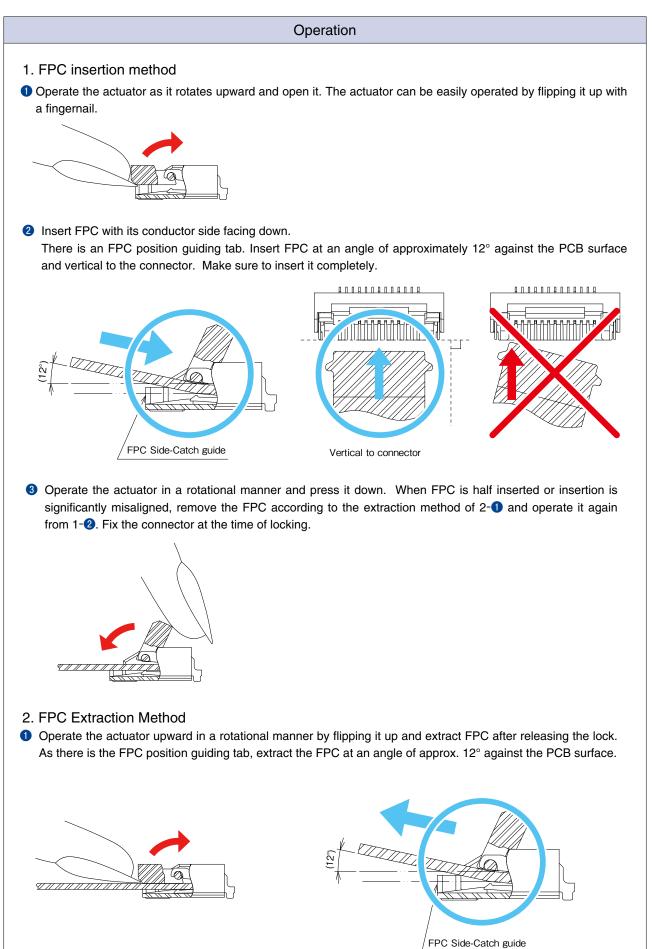
(1.9)

(0.3)

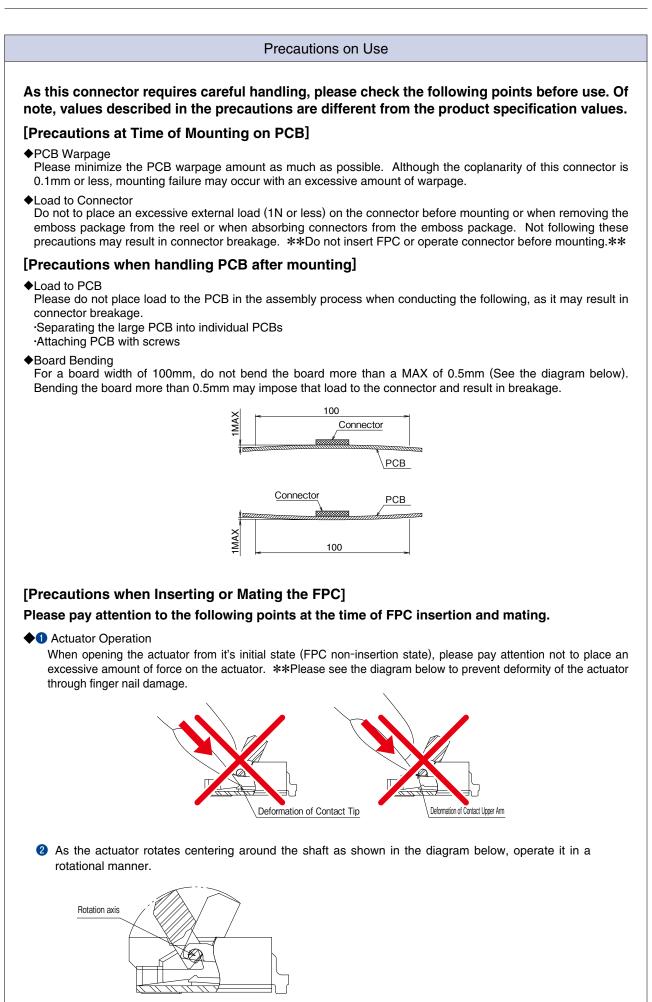
	-								-	-
Part No.	HRS No.	No. of contacts	No. of signal contacts	No. of ground contacts	Н	J	K	L	M	N
FH55-10S-0.5SH	Under planning	10	6	4	8.6	11.5		24	29.4	25.4
FH55-22S-0.5SH	580-3707-7 00	22	14	8	14.6	11.5	—	24	29.4	20.4
FH55-31S-0.5SH	580-3704-9 00	31	20	11	19.1	14.2	28.4	32	37.4	33.4
FH55-40S-0.5SH	580-3700-8 00	40	26	14	23.6	20.2	40.4	44	49.4	45.4
FH55-49S-0.5SH	Under planning	49	32	17	28.1	20.2	40.4	44	49.4	45.4
FH55-61S-0.5SH	Under planning	61	40	21	34.1	26.2	52.4	56	61.4	57.4
FH55M-10S-0.4SH	580-3710-0 00	10	6	4	7.5	11.5		24	29.4	25.4
FH55M-19S-0.4SH	Under planning	19	12	7	11.1	11.5		24	29.4	25.4
FH55M-31S-0.4SH	580-3711-0 00	31	20	11	15.9	14.2	28.4	32	37.4	33.4
FH55M-40S-0.4SH	580-3706-4 00	40	26	14	19.5					
FH55M-49S-0.4SH	Under planning	49	32	17	23.1	20.2	40.4	44	49.4	45.4
FH55M-61S-0.4SH	Under planning	61	40	21	27.9					
FH55M-79S-0.4SH	Under planning	79	52	27	35.1	26.2	52.4	56	61.4	57.4

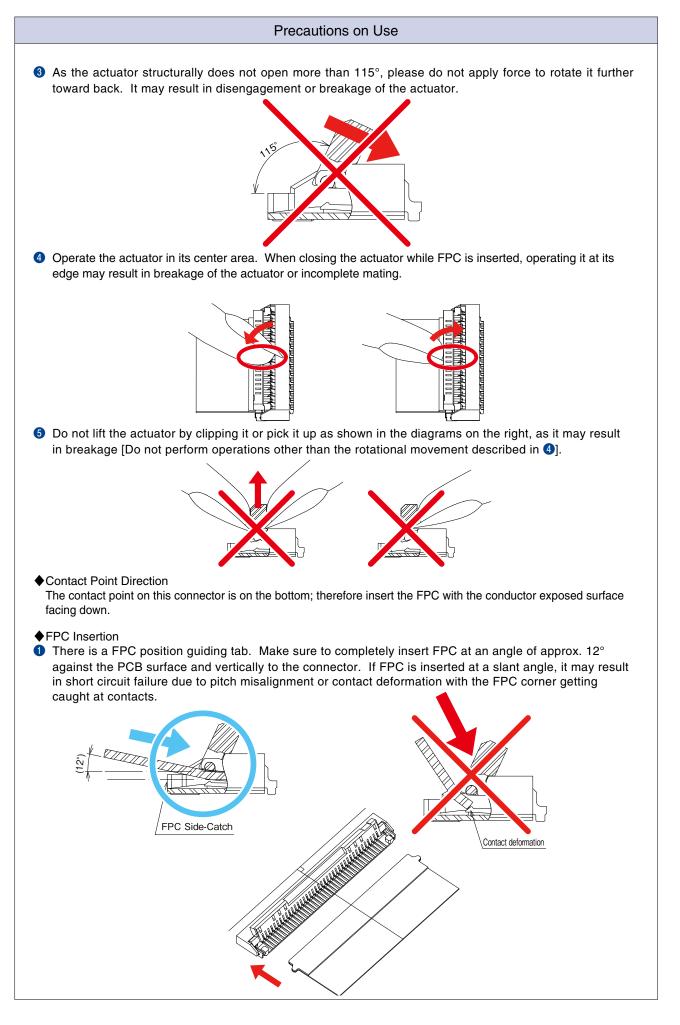
The products above without a HRS No. are currently under planning. Please contact our sales representative for questions concerning the number of contacts.

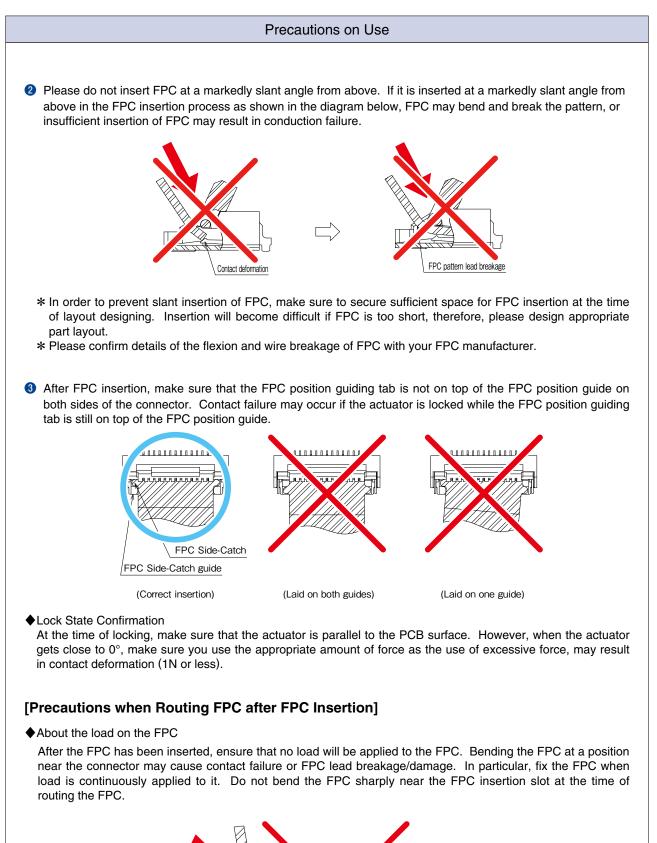
Operation of Connector and Precautions

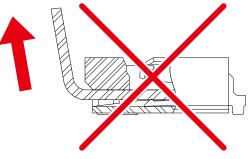


HC5 7









Precautions on Use [Precautions when Removing FPC] • Operate the actuator at the center area when releasing it If you operate the actuator at its edge when releasing the lock while the FPC is inserted, it may result in actuator breakage. • Extracting the FPC while the actuator is unlocked. Since these connectors have FPC position guiding tabs, extract the FPC at an angle of 12° against the PCB.

[Other Precautions]

- Hand Soldering Precautions
 - When hand soldering for repair, etc.:
 - Do not perform reflow or hand soldering with the FPC inserted in the connector.
 - 2 Do not apply excessive heat and make sure that the soldering iron does not touch anywhere other than the connector lead. It may result in connector deformation or melting.

FPC Side-catch

On t supply excessive solder (flux).

If an excessive amount of solder (flux) is supplied to the contact, solder or flux may adhere to the contact points or the shaft of the actuator and can result in contact failure or rotational performance failure of the actuator



MEMO:

HIROSE ELECTRIC CO.,LTD.

2-6-3,Nakagawa Chuoh,Tsuzuki-Ku,Yokohama-Shi 224-8540,JAPAN https://www.hirose.com/

12 RS The characteristics and the specifications contained herein are for reference purpose. Please refer to the latest customer drawings prior to use. The contents of this catalog are current as of date of 07/2023. Contents are subject to change without notice for the purpose of improvements.